

ABSTRACT OF THE DISCLOSURE

A base structure is formed from a green material having first and second opposing sides and having a plurality of via openings therein. The green material is then sintered so that the green material becomes a sintered ceramic material and the base structure becomes a sintered ceramic base structure having the via openings. A conductive via is formed in each via opening of the sintered ceramic base structure. First and second capacitor structures are formed on the sintered ceramic base structure, each on a respective side of the sintered ceramic base structure. The power and ground planes of the capacitor structure are connected to the vias. As such, a capacitor structure can be formed and connected to the vias without the need to drill via openings in brittle substrates such as silicon substrates. Capacitor structures on opposing sides provide more capacitance without manufacturing complexities associated with the manufacture of one capacitor structure having a large number of power and ground planes.